5.0 V ECL Low Impedance Driver

The MC10EL/100EL12 is a low impedance drive buffer. With two pairs of OR/NOR outputs the device is ideally suited for high drive applications such as memory addressing. The device is a function equivalent to the E112 device with higher performance capabilities. With propagation delays significantly faster than the E112, the EL12 is ideally suited for those applications which require the ultimate in AC performance.

The 100 Series contains temperature compensation.

Features

- 290 ps Propagation Delay
- Dual Outputs for 25 Ω Drive Applications
- ESD Protection: Human Body Model; > 1.0 kV Machine Model; > 100 V
- PECL Mode Operating Range: $V_{CC} = 4.2 \text{ V}$ to 5.7 V with $V_{EE} = 0 \text{ V}$
- NECL Mode Operating Range: $V_{CC} = 0 \text{ V}$ with $V_{EE} = -4.2 \text{ V}$ to -5.7 V
- Internal Input Pulldown Resistors
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity Level 1 For Additional Information, see Application Note AND8003/D
- Flammability Rating: UL 94 V-0 @ 0.125 in, Oxygen Index: 28 to 34
- Transistor Count = 44 devices
- Pb-Free Packages are Available

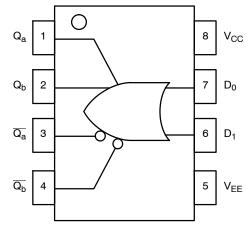


Figure 1. Logic Diagram and Pinout Assignment

1

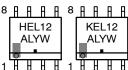


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HEL12 SOIC-8 ALYW **D SUFFIX**



MARKING DIAGRAMS*



CASE 751

TSSOP-8 **DT SUFFIX CASE 948R**







DFN8 **MN SUFFIX** CASE 506AA





MC10 Н = Wafer Lot Κ MC100 Υ = Year 4R MC10 W = Work Week MC100 2F M = Date Code = Assembly Location _ = Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

Table 1. PIN DESCRIPTION

PIN	FUNCTION
D0, D1	ECL Data Inputs
Qa, Qa ; Qb, Qb	ECL Data Outputs
V _{CC}	Positive Supply
V _{EE}	Negative Supply
EP	(DFN8 only) Thermal exposed pad must be connected to a sufficient thermal conduit. Electrically connect to the most negative supply (GND) or leave unconnected, floating open.

Table 2. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	PECL Mode Power Supply	V _{EE} = 0 V		8	V
V _{EE}	NECL Mode Power Supply	V _{CC} = 0 V		-8	V
VI	PECL Mode Input Voltage NECL Mode Input Voltage	V _{EE} = 0 V V _{CC} = 0 V	$\begin{aligned} & V_{I} \leq V_{CC} \\ & V_{I} \geq V_{EE} \end{aligned}$	6 -6	V V
l _{out}	Output Current	Continuous Surge		50 100	mA mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
$\theta_{\sf JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SOIC-8 SOIC-8	190 130	°C/W
θЈС	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-8	41 to 44	°C/W
$\theta_{\sf JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-8 TSSOP-8	185 140	°C/W
$\theta_{\sf JC}$	Thermal Resistance (Junction-to-Case)	Standard Board	TSSOP-8	41 to 44 ± 5%	°C/W
$\theta_{\sf JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	DFN8 DFN8	129 84	°C/W
T _{sol}	Wave Solder Pb Pb-Free	<2 to 3 sec @ 248°C <2 to 3 sec @ 260°C		265 265	°C
$\theta_{\sf JC}$	Thermal Resistance (Junction-to-Case)	(Note 1)	DFN8	35 to 40	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. JEDEC standard multilayer board – 2S2P (2 signal, 2 power)

Table 3. 10EL SERIES PECL DC CHARACTERISTICS V_{CC}= 5.0 V; V_{EE}= 0.0 V (Note 2)

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current		14	17		14	17		14	17	mA
V _{OH}	Output HIGH Voltage (Note 5)	3920	4010	4110	4020	4105	4190	4090	4185	4280	mV
V _{OL}	Output LOW Voltage (Note 3)	3050	3200	3350	3050	3210	3370	3050	3227	3405	mV
V _{IH}	Input HIGH Voltage	3770		4110	3870		4190	3940		4280	mV
V _{IL}	Input LOW Voltage	3050		3500	3050		3520	3050		3555	mV
I _{IH}	Input HIGH Current			150			150			150	μΑ
I _{IL}	Input LOW Current	0.5			0.5			0.3			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 2. Input and output parameters vary 1:1 with V $_{CC}$. V $_{EE}$ can vary +0.06 V / -0.5 V.
- 3. Outputs are terminated through a 50 Ω resistor to V_{CC} 2 volts.

Table 4. 10EL SERIES NECL DC CHARACTERISTICS V_{CC}= 0.0 V; V_{EE}= -5.0 V (Note 4)

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current		14	17		14	17		14	17	mA
V _{OH}	Output HIGH Voltage (Note 5)	-1080	-990	-890	-980	-895	-810	-910	-815	-720	mV
V _{OL}	Output LOW Voltage (Note 5)	-1950	-1800	-1650	-1950	-1790	-1630	-1950	-1773	-1595	mV
V _{IH}	Input HIGH Voltage	-1230		-890	-1130		-810	-1060		-720	mV
V _{IL}	Input LOW Voltage	-1950		-1500	-1950		-1480	-1950		-1445	mV
I _{IH}	Input HIGH Current			150			150			150	μΑ
I _{IL}	Input LOW Current	0.5			0.5			0.3			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 4. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.06 V / -0.5 V.
- 5. Outputs are terminated through a 50 Ω resistor to V_{CC} 2 volts.

Table 5. 100EL SERIES PECL DC CHARACTERISTICS V_{CC}= 5.0 V; V_{EE}= 0.0 V (Note 6)

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current		14	17		14	17		16	20	mA
V _{OH}	Output HIGH Voltage (Note 7)	3915	3995	4120	3975	4045	4120	3975	4050	4120	mV
V _{OL}	Output LOW Voltage (Note 7)	3170	3305	3445	3190	3295	3380	3190	3295	3380	mV
V_{IH}	Input HIGH Voltage	3835		4120	3835		4120	3835		4120	mV
V_{IL}	Input LOW Voltage	3190		3525	3190		3525	3190		3525	mV
I _{IH}	Input HIGH Current			150			150			150	μΑ
I _{IL}	Input LOW Current	0.5			0.5			0.5			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 6. Input and output parameters vary 1:1 with $V_{CC}.\ V_{EE}$ can vary +0.8 V / –0.5 V.
- 7. Outputs are terminated through a 50 Ω resistor to V_{CC} 2 volts.

Table 6. 100EL SERIES NECL DC CHARACTERISTICS V_{CC}= 0.0 V; V_{EE}= -5.0 V (Note 8)

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current		14	17		14	17		16	20	mA
V _{OH}	Output HIGH Voltage (Note 9)	-1085	-1005	-880	-1025	-955	-880	-1025	-955	-880	mV
V _{OL}	Output LOW Voltage (Note 9)	-1830	-1695	-1555	-1810	-1705	-1620	-1810	-1705	-1620	mV
V _{IH}	Input HIGH Voltage	-1165		-880	-1165		-880	-1165		-880	mV
V _{IL}	Input LOW Voltage	-1810		-1475	-1810		-1475	-1810		-1475	mV
I _{IH}	Input HIGH Current			150			150			150	μΑ
I _{IL}	Input LOW Current	0.5			0.5			0.5			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 8. Input and output parameters vary 1:1 with $V_{CC}.\ V_{EE}$ can vary +0.8 V / -0.5 V.
- 9. Outputs are terminated through a 50 Ω resistor to V_{CC} 2 volts.

Table 7. AC CHARACTERISTICS V_{CC} = 5.0 V; V_{EE} = 0.0 V or V_{CC} = 0.0 V; V_{EE} = -5.0 V (Note 9)

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{max}	Maximum Toggle Frequency		TBD			TBD			TBD		GHz
t _{PLH} t _{PHL}	Propagation Delay to Output	120	280	500	180	290	450	210	320	480	ps
t _{JITTER}	Cycle-to-Cycle Jitter		TBD			TBD			TBD		ps
t _r t _f	Output Rise/Fall Times Q (20% - 80%)	150	350	550	150	350	550	150	350	550	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

10.10 Series: V_{EE} can vary +0.06 V / -0.5 V. 100 Series: V_{EE} can vary +0.8 V / -0.5 V.

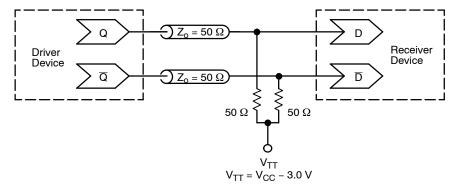


Figure 2. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

ORDERING INFORMATION

Device	Package	Shipping [†]				
MC10EL12D	SOIC-8	98 Units / Rail				
MC10EL12DG	SOIC-8 (Pb-Free)	98 Units / Rail				
MC10EL12DR2	SOIC-8	2500 / Tape & Reel				
MC10EL12DR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel				
MC10EL12DT	TSSOP-8	100 Units / Rail				
MC10EL12DTG	TSSOP-8 (Pb-Free)	100 Units / Rail				
MC10EL12DTR2	TSSOP-8	2500 / Tape & Reel				
MC10EL12DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel				
MC10EL12MNR4	DFN8	1000 / Tape & Reel				
MC10EL12MNR4G	DFN8 (Pb-Free)	1000 / Tape & Reel				
MC100EL12D	SOIC-8	98 Units / Rail				
MC100EL12DG	SOIC-8 (Pb-Free)	98 Units / Rail				
MC100EL12DR2	SOIC-8	2500 / Tape & Reel				
MC100EL12DR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel				
MC100EL12DT	TSSOP-8	100 Units / Rail				
MC100EL12DTG	TSSOP-8 (Pb-Free)	100 Units / Rail				
MC100EL12DTR2	TSSOP-8	2500 / Tape & Reel				
MC100EL12DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel				
MC100EL12MNR4	DFN8	1000 / Tape & Reel				
IC100EL12MNR4G DFN8 (Pb-Free)		1000 / Tape & Reel				

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D - ECL Clock Distribution Techniques

AN1406/D - Designing with PECL (ECL at +5.0 V)

AN1503/D - ECLinPS™ I/O SPICE Modeling Kit

AN1504/D - Metastability and the ECLinPS Family

AN1568/D - Interfacing Between LVDS and ECL

AND8001/D - The ECL Translator Guide
AND8001/D - Odd Number Counters Design

AND8002/D - Marking and Date Codes

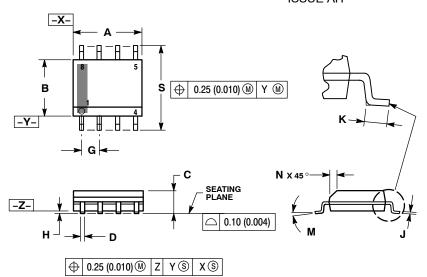
AND8020/D - Termination of ECL Logic Devices

AND8066/D - Interfacing with ECLinPS

AND8090/D - AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

SOIC-8 NB CASE 751-07 **ISSUE AH**

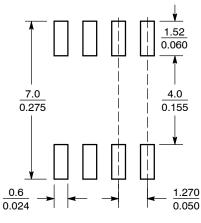


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
- MAXIMUM MATERIAL CONDITION.

 6. 751–01 THRU 751–06 ARE OBSOLETE. NEW STANDARD IS 751–07.

	MILLIN	IETERS	INC	HES		
DIM	MIN	MAX	MIN	MAX		
Α	4.80	5.00	0.189	0.197		
В	3.80	4.00	0.150	0.157		
С	1.35	1.75	0.053	0.069		
D	0.33	0.51	0.013	0.020		
G	1.27	7 BSC	0.050 BSC			
Н	0.10	0.25	0.004	0.010		
J	0.19	0.25	0.007	0.010		
K	0.40	1.27	0.016	0.050		
М	0 °	8 °	0 °	8 °		
N	0.25	0.50	0.010	0.020		
S	5.80	6.20	0.228	0.244		

SOLDERING FOOTPRINT*

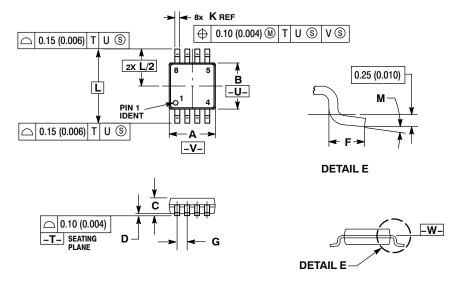


 $\left(\frac{\text{mm}}{\text{inches}}\right)$ SCALE 6:1

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP-8 **DT SUFFIX** PLASTIC TSSOP PACKAGE CASE 948R-02 **ISSUE A**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH.
 PROTRUSIONS OR GATE BURRS. MOLD FLASH
 OR GATE BURRS SHALL NOT EXCEED 0.15
 (0.006) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE INTERLEAD
 FLASH OR PROTRUSION. INTERLEAD FLASH OR
 PROTRUSION SHALL NOT EXCEED 0.25 (0.010)
 PER SIDE.

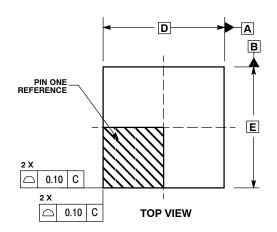
 5. TERMINAL NUMBERS ARE SHOWN FOR
 REFERENCE ONLY.

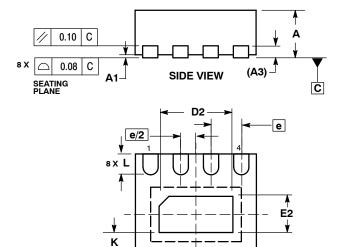
 6. DIMENSION A AND B ARE TO BE DETERMINED
 AT DATUM PLANE -W-.

	MILLIN	METERS	INCHES				
DIM	MIN	MAX	MIN	MAX			
Α	2.90	3.10	0.114	0.122			
В	2.90	3.10	0.114	0.122			
С	0.80	1.10	0.031	0.043			
D	0.05	0.15	0.002	0.006			
F	0.40	0.70	0.016	0.028			
G	0.65	BSC	0.026	BSC			
K	0.25	0.40	0.010	0.016			
L	4.90	BSC	0.193 BSC				
М	0 °	6 °	0 °	6°			

PACKAGE DIMENSIONS

DFN8 CASE 506AA-01 ISSUE D





NOTES:

- DIMENSIONING AND TOLERANCING PER
 ASME Y14.5M, 1994.
- ASME Y14.3M, 1994.

 2. CONTROLLING DIMENSION: MILLIMETERS.

 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.

 4. COPLANARITY APPLIES TO THE EXPOSED DAD A COMPTL AS THE TERMINAL.
- PAD AS WELL AS THE TERMINALS.

	MILLIMETERS							
DIM	MIN	MAX						
Α	0.80	1.00						
A1	0.00	0.05						
А3	0.20	0.20 REF						
b	0.20	0.30						
D	2.00	BSC						
D2	1.10	1.30						
Е	2.00	BSC						
E2	0.70	0.90						
е	0.50	BSC						
K	0.20							
L	0.25	0.35						

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CAB

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